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Press Release

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New Self-Leveling Material Flows Around Tight Spaces to Provide Excellent Thermal Transfer

Henkel's Gap Filler 1400SL Offers Robust Thermal Performance and Void Filling Capabilities

Henkel Adhesive Technologies continues to expand its thermal materials portfolio and today announced the development and commercialization of Gap Filler 1400SL. An evolution in thermal interface materials, Gap Filler 1400SL combines the properties of low viscosity and, relative to conventional self-leveling products, comparatively high thermal conductivity in a unique formula designed to accommodate challenging architectures.

A two-part, silicone-based, liquid gap filling material, Gap Filler 1400SL has extremely low viscosity which allows the material to flow in and around tight, uniquely shaped structures to fill small voids and provide excellent thermal transfer. With a thermal conductivity of 1.4W/m-K, Gap Filler 1400SL unites high thermal conductivity and exceptional flow – characteristics that have traditionally been mutually exclusive – to allow new levels of design latitude.

"Previously, electronics professionals relied on conductive potting compounds with comparatively low thermal conductivity," explains Lonnie Helgeson, Henkel Product Manager for Gap Filler materials. "Manufacturers no longer have to sacrifice viscosity or thermal conductivity. With Gap Filler 1400SL, these properties are united in a novel material that is self-leveling and also delivers shock and vibration dampening."

When cured, Gap Filler 1400SL is exceptionally soft, allowing for absorption of coefficient of thermal expansion (CTE) stresses and providing mechanical shock dampening for fragile assemblies. The material is ideal for multiple applications including high power components such as FETs, industrial controllers with transient loads and automotive electronics like DC-DC converters for hybrid vehicles.

“Gap Filler 1400SL is also a low volatility material,” adds Helgeson. “For any application where fogging from outgassing is a concern, this product’s low-VOC formulation helps improve this issue.”

Cured at room temperature with no byproducts, Gap Filler 1400SL provides consistent curing throughout the compound with no restrictions on thickness and the ability to accelerate curing with exposure to elevated temperature.

Complete Gap Filler 1400SL information is available at www.bergquistcompany.com.

About Henkel

Henkel operates worldwide with leading brands and technologies in three business units: Laundry & Home Care, Beauty Care and Adhesive Technologies. Founded in 1876, Henkel holds globally leading market positions, both in the consumer and in the industrial businesses, with well-known brands such as Persil, Schwarzkopf and Loctite. Henkel employs about 50,000 people and reported sales of 16.4 billion euros and adjusted operating profit of 2.6 billion euros in fiscal 2014. Henkel’s preferred shares are listed in the German stock index DAX.

Photo material is available at http://www.henkel.com/press

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The following material is available:

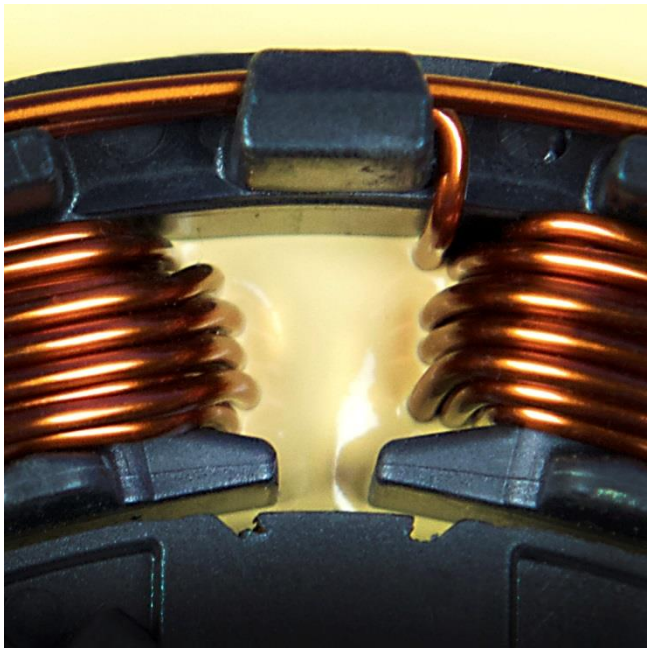

Figure 1: Henkel's Gap Filler 1400SL combines good thermal performance with exceptional flow and void filling characteristics.